

What is claimed is:

1. A light emitting diode device comprising:
 - a circuit substrate;
 - an LED mounted on the circuit substrate;
 - 5 a resin layer encapsulating the LED;
 - a reflection layer provided on the resin layer for reflecting lights emitted from the LED.
2. The device according to claim 1 further comprising a lower reflection film formed on the upper 10 surface of the circuit substrate.
3. The device according to claim 1 wherein the reflection layer is provided for partly transmitting the lights emitted from the LED.
4. The device according to claim 1 wherein the 15 reflection layer comprises a transparent holding plate and an upper reflection film provided between the upper surface of the resin layer and the underside of the holding plate.
5. The device according to claim 4 wherein the upper reflection film is formed by a metal plating.
- 20 6. The device according to claim 4 wherein the upper reflection film has an area smaller than an area of the resin layer.